

IN THE CLAIMS:

Please amend claims 39, 52 and 58 as follows:

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39. **(Thrice Amended)** A method of mounting an electronic component, said method comprising:
aligning in position bumps formed by wire-bonding on electrodes of said electronic component with electrodes of a circuit board, with interposition between said electronic component and said circuit board of insulative solid thermosetting resin;
softening to flow up to an edge of said electronic component, and then hardening, with heat, said thermosetting resin interposed between said electronic component and said circuit board, while achieving mutual pressing between said electronic component and said circuit board at a pressure of force of at least 20 gf per bump during leveling of said bumps and correcting of any warping of said circuit board, thereby bonding said electronic component and said circuit board together to achieve electrical connection between said mutual electrodes thereof; and
said hardening, said leveling and said correcting being achieved at approximately the same time.

52. **(Thrice Amended)** A method of mounting an electronic component, said method comprising:
aligning in position electrodes of said electronic component with electrodes of a circuit board, with interposition between said electronic component and said circuit board of insulative solid thermosetting resin;
softening to flow up to an edge of said electronic component, and then hardening, with heat, said thermosetting resin interposed between said electronic component and said circuit board, while achieving mutual pressing between said electronic component and said circuit board during correcting of any warping of said circuit board, thereby bonding said

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electronic component and said circuit board together to achieve electrical connection between said mutual electrodes thereof;

wherein, prior to said aligning, said thermosetting resin, in the form of a solid thermosetting resin sheet having holes formed at positions corresponding to said electrodes of said circuit board and extending in a direction of extension of said electrodes, with particles being embedded and electrically continuous in said holes, said particles comprising resin balls having surfaces plated with gold, nickel particles, conductive particles made of silver, silver-palladium or gold, conductive paste, or gold balls, is applied to said electrodes of said circuit board by positional alignment, and said bonding is executed by said hardening said sheet by application of heat thereto while conducting said pressing by forcing said electronic component toward said circuit board; and

wherein each of said particles has a size greater than a thickness of a passivation film to be coated on at least said electrodes of said electronic component and smaller than a thickness of one of said electrodes of said circuit board, and said bonding further is executed by applying ultrasonic vibrations to said electronic component.

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58. **(Thrice Amended)** An apparatus to mount an electronic component to a circuit board, said apparatus comprising:

a positional alignment device to align in position bumps formed by wire-bonding on electrodes of the electronic component with electrodes of the circuit board, with interposition between the electronic component and the circuit board of insulative solid thermosetting resin;

a heating device to soften to flow up to an edge of the electronic component, and then harden, with heat, the thermosetting resin interposed between the electronic component and the circuit board; and

a pressing device to achieve mutual pressing between the electronic component and the circuit board at a pressure force of at least 20 gf per bump during leveling of the

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bumps and correcting of any warping of the circuit board, thereby bonding the electronic component and the circuit board together to achieve electrical connection between the mutual electrodes thereof; and

said heating device and said pressing device achieving the hardening of the thermosetting resin, the leveling of the bumps and the correcting of the warping at approximately the same time.

Kindly add the following new claims 89, 90, 91, 92 and 93:

89. The method according to claim 39, wherein
aligning in position bumps on electrodes of said electronic component with electrodes of a circuit board comprises aligning said bumps with said electrodes on said circuit board while holding said electronic component with a heated bonding tool, softening to flow up to an edge of said electronic component, and then hardening, with heat, said thermosetting resin interposed between said electronic component and said circuit board comprises transferring heat from said heated bonding tool to said thermosetting resin, and

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90. The method according to claim 52, wherein
aligning in position electrodes of said electronic component with electrodes of a circuit board comprises aligning said electrodes of said electronic component with said electrodes on said circuit board while holding said electronic component with a heated bonding tool,

softening to flow up to an edge of said electronic component, and then hardening, with heat, said thermosetting resin interposed between said electronic component and said

circuit board comprises transferring heat from said heated bonding tool to said thermosetting resin, and

achieving mutual pressing between said electronic component and said circuit board comprises using said heated bonding tool to force said electronic component against said thermosetting resin.

91. The method according to claim 39, wherein said solid thermosetting resin includes an inorganic filler.

92. The method according to claim 52, wherein said solid thermosetting resin includes an inorganic filler.

93. The apparatus according to claim 58, wherein the solid thermosetting resin includes an inorganic filler.